This 2.5 day Conference will include Invited Presentations, Solicited Presentations, Posters, and a Special Panel Session on “Future Directions for 3DIC”. Attendees can also participate in a tour of Tyndall’s state-of-the-art facilities for materials synthesis, fabrication, packaging and characterisation of microelectronics, MEMS and photonics materials, devices and circuits.

Call for Presentations and Posters

**Technology:** Materials, Equipment, Wafer-handling, Substrates, Through Silicon Vias (TSV), Alignment, Bonding/De-bonding (Thermo-Compression, Electrostatic, Hybrid, Temporary Adhesive), Wafer Cleaning, Thinning, Dicing, Multilevel Epitaxial Growth,

2.5D/3D Integration (Monolithic, Heterogeneous), Interposers (Passive, Active), Chiplets, Micro-Transfer Printing

Capacitive Coupling, Inductive Coupling, Optical Coupling etc.

**Design and CAD:** Synthesis, design flows, signal design, power integrity, thermal considerations, mechanical stress, reliability, test, techniques, analysis, etc.

**Applications:** Imaging, Memory, Processors, SOC, DSP, FPGA, SOI, Artificial Intelligence/Machine Learning, Communications, Networking, Biomedical, Sensors, MEMS, Wireless, Mixed-Signal/Analog Circuits, RF, Microwave, Millimeter Wave, Photonics/Optoelectronics, Integrated Photonics Electronics, Integrated Passives, Integrated Power Management etc.

**Also soliciting proposals for tutorials, panels, and workshop presentations**

To propose an idea for a tutorial please contact the conference organizers

Veda Sandeep Nagaraja (TNI) [veda.sandeep@tyndall.ie](mailto:veda.sandeep@tyndall.ie)

Cian Ó Murchú (TNI)

For more details, visit the conference website [www.3dic-conf.org](http://www.3dic-conf.org)